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APPLICATION NO.			Alexandria, Virginia 22313-145 www.uspto.gov	50
	FILING DATE	FIRST NAMED INVENTOR		
10/081,425	02/22/2002		ATTORNEY DOCKET NO.	CONFIRMATION NO.
HAYNES BEI P O BOX 366	90 09/23/2003 FFEL & WOLFELD Ll BAY, CA 94019	Rajendra Pendse	CPAC 1011-2 US 9980 EXAMINER GEYER, SCOTT B	
			ART UNIT 2829 DATE MAILED: 09/23/2003	PAPER NUMBER

Please find below and/or attached an Office communication concerning this application or proceeding.

Period for Reply	10/081,425 Examiner	Applicant(s) PENDSE, RAJENDI	RA		
The MAILING DATE of this communication appe Period for Reply	Examiner		RA		
Period for Reply					
Period for Reply	SCOUR GOVE	Art Unit			
4.000=	Scott B. Geyer	2829			
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1361 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply w - If NO period for reply is specified above, the maximum statutory period will - Failure to reply within the set or extended period for reply will, by statute, ca - Any reply received by the Office later than three months after the mailing da Status Status	IS SET TO EXPIRE 3 MON (a). In no event, however, may a reply rithin the statutory minimum of thirty (30	TH(S) FROM be timely filed			
1) Responsive to communication(s) filed on <u>07 Aug</u>					
3) Since this application is in condition (action is non-final.				
3) Since this application is in condition for allowance closed in accordance with the practice under Ex Disposition of Claims	ce except for formal matters parte Quayle, 1935 C.D. 11	, prosecution as to the m I, 453 O.G. 213.	nerits is		
4) Claim(s) 1,3-7 and 12-17 is/are pending in the ap	nlication				
4a) Of the above claim(s) is/are withdrawn to	from consideration				
5) Claim(s) is/are allowed.	non consideration.				
6)⊠ Claim(s) <u>1,4-7,12 and 14-17</u> is/are rejected.					
/)⊠ Claim(s) <u>3 and 13</u> is/are objected to.					
8) Claim(s) are subject to restriction and/s	action was a				
• -	ction requirement.				
9) The specification is objected to by the Examiner.					
10) The drawing(s) filed on 19 May 2003 is/are: a) Acc	cented or b) Cobineted to the				
S Octobri filed Off	all (approved b)[7] if	See 37 CFR 1.85(a).			
		oved by the Examiner.			
The ball of declaration is objected to by the Examin	er.				
Priority under 35 U.S.C. §§ 119 and 120					
13) Acknowledgment is made of a claim for foreign prior a) All b) Some * c) None of	rity under 35 H.S.C. \$ 440/-	A (1) (-			
, and the off		1)-(a) or (f).			
1. Certified copies of the priority documents have	e been received				
2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents.					
application from the later of the priority do	cuments have been receive	ed in this National Ot-			
The same of the delical line and the	00ml(E) = -1 .	d.			
and the desired that the desired of a claim for domestic prior	ity under 25 LLC O. a		eation)		
a) The translation of the foreign language provisions 15) Acknowledgment is made of a claim for domestic prior	al application has been rece	eived.	alionj.		
15) Acknowledgment is made of a claim for domestic prior ttachment(s)	ity under 35 U.S.C. §§ 120	and/or 121.			
Notice of References Cited (PTO 900)	_				
Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	4) Interview Summary	(PTO-413) Paper No(s)			
I IIIOIIIation Disclosure Statement(s) (PTO 1440) P 1	5) Notice of Informal Pa	atent Application (PTO-152)	-		

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after allowance or after an Office action under *Ex Parte Quayle*, 25 USPQ 74, 453 O.G. 213 (Comm'r Pat. 1935). Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, prosecution in this application has been reopened pursuant to 37 CFR 1.114. Applicant's submission filed on August 7, 2003 has been entered.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1, 4-7, 12 and 14-17 are rejected under 35 U.S.C. 102(b) as being anticipated by Lake (6,087,731).

As to *claims 1, 12 and 15*, Lake teaches a method of encapsulating flip chip interconnects comprising application of a limited quantity of resin 32 (see figure 4) to the interconnect bumps 24 of a IC chip 20,22. The step of applying resin, as taught by Lake, comprises dipping the IC chip with interconnect bumps 24 into a pool of the resin

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32 and then withdrawing the IC chip from the pool of resin 32. Thereafter, the IC chip device can be bonded to other substrates.

As to claims 4 and 14, Lake teaches a method of encapsulating flip chip interconnects wherein the depth of the resin pool is such that the surface of the IC chip device does not touch the pool of resin.

As to *claim 5*, Lake teaches the reservoir of resin in figures 4 and 5 wherein the reservoir has a bottom 34 and wherein the resin pool 32 has a depth. The interconnect bumps are dipped into the pool such that the bumps contact the bottom surface 34 (see figure 6), after which the bumps are withdrawn from the pool of resin.

As to claims 6 and 16, Lake teaches the depth of the pool of resin 32 is approximate the standoff height (see figures 4-6).

As to *claims* 7 *and* 17, Lake teaches the depth of the pool of resin 32 is less than the standoff height, such that the bottom surface of the chip does not contact the pool of resin 32 (see figures 4-6).

Allowable Subject Matter

Claims 3 and 13 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The prior art of record and to the examiner's knowledge does not teach or render obvious, at least to the skilled artisan, the instant invention regarding dipping an IC chip into a pool of resin where the depth of the pool of resin approximates a bump standoff height, such that when the chip with interconnects

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is withdrawn from the pool of resin, a quantity of the resin remains on the chip surface

as well as the chip interconnects.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Scott B. Geyer whose telephone number is (703) 306-5866. The examiner can normally be reached on weekdays, between 10:00am - 6:30pm. E-mail: scott.geyer@uspto.gov

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on (703) 308-1233. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

SBG

SBG September 22, 2003 EVAN PERT
PRIMARY EXAMINER

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